2SC3506

Silicon NPN triple diffusion planar type

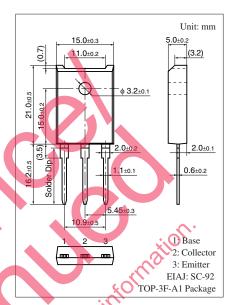
For high-speed switching

■ Features

- High-speed switching
- High collector-base voltage (Emitter open) V_{CBO}
- Satisfactory linearity of forward current transfer ratio h_{FE}
- Full-pack package which can be installed to the heat sink with one

■ Absolute Maximum Ratings $T_C = 25$ °C

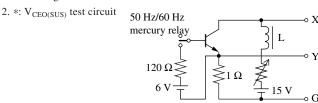
Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V _{CBO}	1 000	V	
Collector-emitter voltage (E-B short)	V _{CES}	1 000	V	
Collector-emitter voltage (Base open)	V _{CEO}	800	V	
Emitter-base voltage (Collector open)	V_{EBO}	7	V	
Collector current	I_C	3	A	
Base current	I_{B}	2	A	
Peak collector current	I _{CP}	6	A	
Collector power dissipation	P _C	70	W	
$T_a = 25$ °C		3.0		
Junction temperature	$T_{\rm j}$	150	°C	
Storage temperature	T_{stg}	-55 to +150	°C	



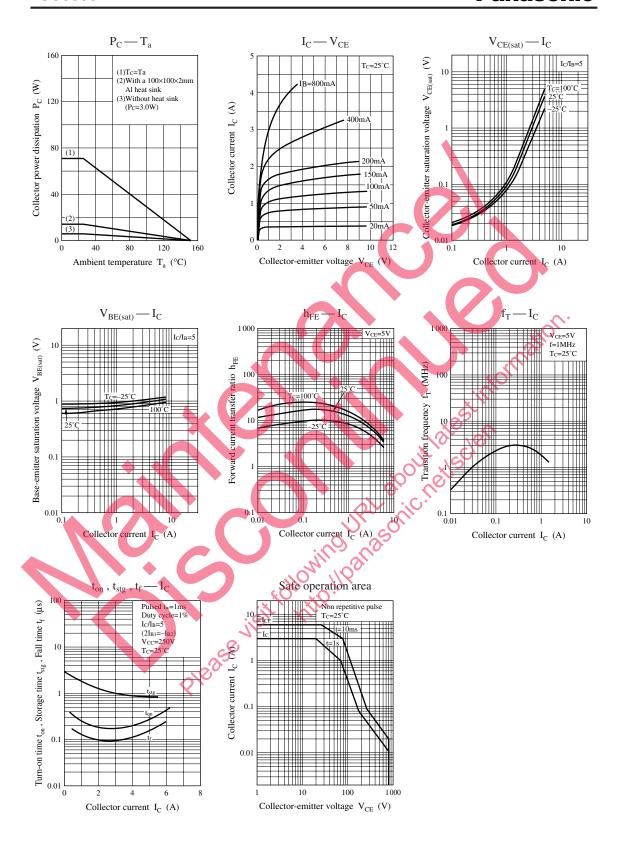
■ Electrical Characteristics $T_C = 25^{\circ}C \pm 3^{\circ}C$

Base current	I_{B}	2 A		11/2					
Peak collector current	I_{CP}	6 A	S						
Collector power dissipation	Pc	70 W	Xes	20					
$T_a = 25^{\circ}C$		3.0	it is a	0.					
Junction temperature	T _j	150 °C	100 x180						
Storage temperature	T _{stg}	-55 to +150 °C	2, 60						
Base current Peak collector current I_{CP}									
■ Electrical Characteristics T _C = 25°C ± 3°C									
Parameter	Symbol	Conditions	Min	Тур	Max	Unit			
Collector-emitter sustaining voltage *	V _{CEO(SUS)}	$I_C = 0.5 \text{ A}, L = 50 \text{ mH}$	800			V			
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = 1000 \text{ V}, I_{E} = 0$			50	μΑ			
Emitter-base cutoff current (Collector open)	I_{EBO}	$V_{EB} = 7 \text{ V/V} = 0$			50	μΑ			
Forward current transfer ratio	h _{FE}	$V_{CE} = 5 \text{ V}, I_{C} = 2 \text{ A}$	6			_			
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = 2 A, I_B = 0.4 A$			1.5	V			
Base-emitter saturation voltage	VBE(sat)	$I_C = 2 A, I_B = 0.4 A$			1.5	V			
Transition frequency	f_T	$V_{CE} = 5 \text{ V}, I_C = 0.2 \text{ A}, f = 1 \text{ MH}$	Iz	4		MHz			
Turn-on time	t _{on}	t_{on} $I_C = 2 A$			1	μs			
Storage time	t _{stg}	$I_{B1} = 0.4 \text{ A}, I_{B2} = -0.8 \text{ A}$			2.5	μs			
Fall time	t _f	$V_{CC} = 250 \text{ V}$			0.5	μs			

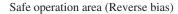
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

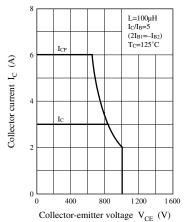


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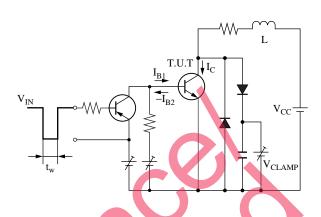


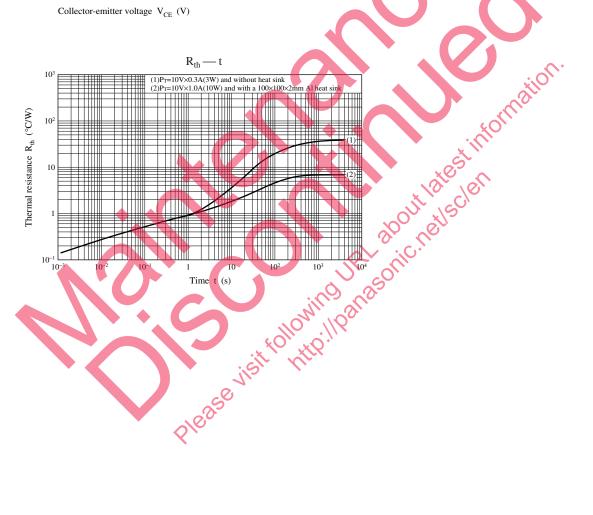
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Safe operation area (Reverse bias) measurement circuit





SJD00105BED 3

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